

CLAIMS

What is claimed is:

1. A method of fabricating an integrated circuit package comprising:
providing a first leadframe and a second leadframe;
laminating said second leadframe to a portion of said first leadframe in order to create a multi-layer laminated leadframe; and
mounting a semiconductor die on another portion of said first leadframe.
2. The method of fabricating an integrated circuit package according to claim 1, further comprising mounting a plurality of contact balls on said semiconductor die.
3. The method of fabricating an integrated circuit package according to claim 1, further comprising:
providing a third leadframe; and
laminating said third leadframe on at least a portion of said semiconductor die.
4. The method of fabricating an integrated circuit package according to claim 1, wherein said first leadframe comprises a copper strip having silver plating on a first surface and solder plating on an opposing second surface thereof.
5. The method of fabricating an integrated circuit package according to claim 1, wherein said second leadframe comprises a copper strip having solder plating on first and second surfaces thereof.
6. The method of fabricating an integrated circuit package according to claim 3, wherein said third leadframe comprises a copper strip having solder plating on first and second surfaces thereof.
7. The method of fabricating an integrated circuit package according to claim 1, wherein said second leadframe is laminated to said first leadframe via solder reflow technique.
8. The method of fabricating an integrated circuit package according to claim 3, wherein said third leadframe is laminated to said semiconductor die via solder reflow technique.

9. The method of fabricating an integrated circuit package according to claim 1 wherein said semiconductor die is coated with at least one of titanium, tungsten, gold, or a combination thereof for soldering.
10. An integrated circuit package comprising:
a first leadframe;
a second leadframe laminated to a portion of said first leadframe in order to create a multi-layer laminated leadframe; and
a semiconductor die mounted to another portion of said first leadframe.
11. The integrated circuit package according to claim 10, further comprising a plurality of contact balls mounted on said semiconductor die.
12. The integrated circuit package according to claim 10, further comprising:
a third leadframe laminated to at least a portion of said semiconductor die.
13. The integrated circuit package according to claim 10, wherein said first leadframe comprises a copper strip having silver plating on one surface and said second leadframe is soldered to an opposing second surface thereof.
14. The integrated circuit package according to claim 10, wherein said second leadframe comprises a copper strip having solder plating on one surface and being soldered to said first leadframe on an opposing second surface thereof.
15. The integrated circuit package according to claim 12, wherein said third leadframe comprises a copper strip having solder plating on one surface and being soldered to said first leadframe on an opposing second surface thereof.
16. The integrated circuit package according to claim 10 wherein said semiconductor die is coated with at least one of titanium, tungsten, gold, or a combination thereof for soldering.